

Processing/Physical Characteristics	dry / cond	Unit	Test Standard
ISO Data			
^[C] Molding shrinkage, parallel	0.3 / *	%	ISO 294-4, 2577
^[C] Molding shrinkage, normal	1.0 / *	%	ISO 294-4, 2577

[C]: CAMPUS

Mechanical properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Tensile Modulus	10800 / 8000	MPa	ISO 527
^[C] Stress at break	105 / 75	MPa	ISO 527
^[C] Strain at break	1.5 / 2.5	%	ISO 527
^[C] Charpy impact strength, +23°C	33 / 33	kJ/m ²	ISO 179/1eU

[C]: CAMPUS

Thermal properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Melting temperature, 10°C/min	263 / *	°C	ISO 11357-1/-3
^[C] Temp. of deflection under load, 1.80 MPa	243 / *	°C	ISO 75-1/-2
^[C] Temp. of deflection under load, 0.45 MPa	262 / *	°C	ISO 75-1/-2
^[C] Burning Behav. at thickness h	V-0 / *	class	IEC 60695-11-10
Thickness tested	0.8 / *	mm	-
Yellow Card available	yes / *	-	-
^[C] Burning Behav. 5V at thickness h	5VA / *	class	IEC 60695-11-20
Thickness tested	1.5 / *	mm	-

[C]: CAMPUS

Electrical properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Electric strength	37 / -	kV/mm	IEC 60243-1
^[C] Comparative tracking index	600 / -	-	IEC 60112

[C]: CAMPUS

Other properties	dry / cond	Unit	Test Standard
^[C] Density	1460 / -	kg/m ³	ISO 1183

[C]: CAMPUS

Characteristics

Processing
Injection Molding

Applications
Electrical and Electronical

Special Characteristics
Flame retardant, Halogen-free, Phosphorus-free